

## 2 **Commissioning of the highly granular SiW-ECAL** 3 **technological prototype**

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5 **ABSTRACT:** High precision physics at future colliders as the International Linear Collider (ILC)  
6 require unprecedented high precision in the determination of the final state of the particles produced  
7 in the collisions. This precision will be achieved thanks to the Particle Flow algorithms (PF)  
8 which require compact, highly granular and hermetic calorimeters systems. The Silicon-Tungsten  
9 Electromagnetic Calorimeter (SiW-ECAL) technological prototype design and R&D is oriented  
10 at the baseline design of the ECAL of the International Large Detector (ILD) for the ILC. In this  
11 article we present the commissioning and the performance of the prototype in a beam test carried  
12 at DESY in June 2017.

13 **KEYWORDS:** Calorimeter methods, calorimeters, Si and pad detectors

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36 **1 Introduction**

37 Future accelerator based particle physics experiments require very precise and detailed reconstruction  
38 of the final states produced in the beam collisions. A particular example is the next generation  
39 of  $e^+e^-$  linear colliders such the ILC[1–5]. This project will provide collisions of polarized beams  
40 with center-of-mass energies of 250 GeV - 1 TeV. These collisions will be studied by two multipur-  
41 pose detectors: the International Large Detector (ILD) and the Silicon Detector (SiD)[5]. To meet  
42 the precision levels required by the ILC physics goals, new techniques relying on single particle  
43 separation to make possible the choice of the best information available in the full detector to  
44 measure the energy of the final state objects have been developed. These techniques are called

45 Particle Flow (PF) techniques [6–8] and allow to reduce the impact of the poor resolution of the  
46 calorimeter systems (compared with trackers) in the overall reconstruction. The PF algorithms  
47 impose some special requirements in the design of the detectors. For example, it requires highly  
48 granular, compact and hermetic calorimeters.

49 The CALICE collaboration is driving most of the efforts on R&D of highly granular calorime-  
50 ters [8] for future linear colliders by investigating and building prototypes for several calorimeter  
51 concepts. One of these calorimeters is the silicon-tungsten electromagnetic calorimeter, SiW-  
52 ECAL. The SiW-ECAL is the baseline choice for the ILD electromagnetic calorimeter. It has  
53 silicon (Si) as active material and tungsten (W) as absorber material, amounting up to  $24 X_0$  of  
54 thickness which corresponds to  $\sim 1 \lambda_I$  (interaction length). The combination of Si and W choices  
55 makes possible the design and construction of a very compact calorimeter with highly granular  
56 and compact active layers: 30 layers in total in the barrel region in modules of 20 cm thick. It  
57 will be built an alveolar structure of carbon fiber into which modules made of tungsten plates and  
58 the active sensors will be inserted. The very-front-end (VFE) electronics will be embedded in  
59 the detector units. The silicon sensors will be segmented in squared cells (or channels) of 5x5  
60 mm: a total of  $\sim 100$  million readout channels will constitute the ECAL for ILD and a density of  
61 channels of 6000 channels/dm<sup>3</sup> in the barrel. The desired signal dynamic range in each channel  
62 goes from 0.5 MIP to 3000 MIPs, where the MIP acronym stands for the energy deposited by a  
63 minimum-ionizing-particle. To reduce overall power consumption, the SiW-ECAL will exploit  
64 the special bunch structure foreseen for the ILC: the  $e^+e^-$  bunches trains will arrive in spills of  $\sim 1$ -  
65 ms width separated by  $\sim 200$  ms. The data acquisition will be gated during these short windows and  
66 during the idle time the bias currents of the electronics will be shut down. This technique is usually  
67 denominated power pulsing. In addition to this, to cope with the large amount of channels, the  
68 calorimeters should work in self-trigger mode (each channel featuring an internal trigger decision  
69 chain) and zero suppression mode.

## 70 **2 The SiW-ECAL technological prototype**

71 The first SiW-ECAL prototype was the so called SiW-ECAL physics prototype. It was success-  
72 fully tested at DESY, FNAL and CERN running in front of another prototype from the CALICE  
73 collaboration, the analogue hadronic calorimeter AHCAL, delivering the proof of concept of the  
74 technology and the PF calorimetry. For the physics prototype, the VFE was placed outside the  
75 active area with no particular constraints in power consumption. It consisted of 30 layers of Si as  
76 active material alternated with tungsten plates as absorber material. The active layers were made of  
77 a matrix of 3x3 Si wafers of 500  $\mu\text{m}$  thickness. Each of these wafers was segmented in matrices of  
78 6x6 squared channels of 1x1  $\text{cm}^2$ , allowing for a potential density of 1500 channels/dm<sup>3</sup> assuming  
79 the ILD baseline design constraints on the material repartition and compactness. The prototype  
80 was divided in 3 modules of 10 layers with different W depth per layer in each of these modules  
81 (0.4, 1.6 and 2.4  $X_0$ ) making a total of  $24 X_0$ . That very first prototype offered a signal over noise  
82 on the measured charge of 7.5 for MIP like particles. More results proving the good performance  
83 of the technology and the PF can be found in references [9–14].

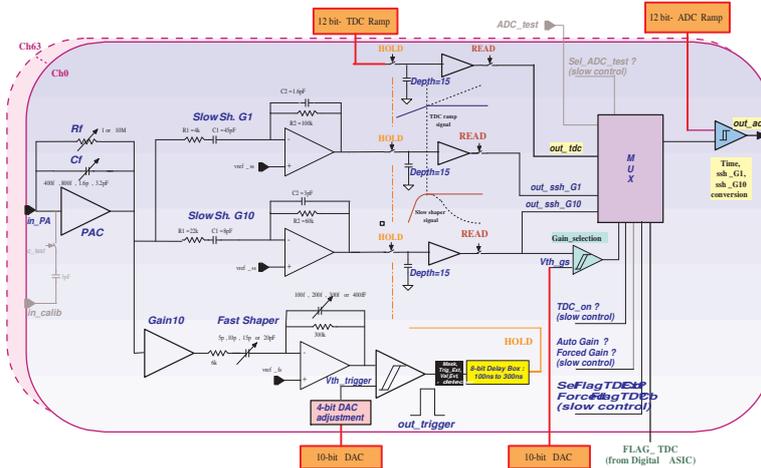
84 The current prototype is called the SiW-ECAL technological prototype. It addresses the main  
85 technological challenges: compactness, power consumption reduction through power pulsing and

86 VFE inside the detector close to real ILD conditions. It will also provide data to deeply study  
 87 the PF and provide input to tune simulation programs as for example GEANT4[15–17] which is  
 88 widely used in particle physics to simulate the passage of particles through matter. In this section  
 89 we described in detail the main features and characteristics of the technological prototype.

90 **2.1 Silicon sensors**

91 The sensors consist of high resistivity (bigger than  $5000 \Omega\cdot\text{cm}$ ) silicon wafers with a thickness of  
 92  $320\mu\text{m}$ . The size of the wafers is  $9 \times 9 \text{ cm}^2$  and each of them is subdivided in an array of 256  
 93 PIN diodes of  $5 \times 5 \text{ mm}^2$ . A MIP traversing the PIN parallel to its normal will create  $\sim 80 h^+e^-$   
 94 pairs per  $\mu\text{m}$  which corresponds to 4.1 fC for particles incident perpendicularly to its surface. The  
 95 original design of the silicon wafers included an edge termination made of floating guard-rings. It  
 96 was observed in beam tests [18, 19] that the capacitive coupling between such floating guard-rings  
 97 and the channels at the edge created not negligible rates off fake events in tests with high energy  
 98 beams (pions and electrons with energies larger than 20-40 GeV) An R&D program together with  
 99 Hamamatsu Photonics (HPK Japan) was conducted to study the guard-rings design as well as the  
 100 internal crosstalk. It was concluded that using wafers without guard rings and with a width of the  
 101 peripheral areas lower than  $500\mu\text{m}$  thanks to the use of stealth dicing technique, the amount of these  
 102 squared events can be reduced to be at negligible level. For the setup described this article we used  
 103 different solutions for the edge terminations. For all of them, the expected levels of fake events  
 104 are negligible due to the low energy of the interactions studied in this paper: MIP like particles or  
 105 electromagnetic showers created by particles of few GeV from the DESY beam. Therefore, they  
 106 are not further discussed here.

107 **2.2 SKIROC: Silicon pin Kalorimeter Integrated ReadOut Chip**



**Figure 1.** The schematics of the analog part of SKIROC2. High-stack picture (right bottom corner)

108 The SKIROC[20] (Silicon pin Kalorimeter Integrated ReadOut Chip) is a very front end ASIC  
 109 (application-specific integrated circuits) designed for the readout of silicon PIN diodes. In its  
 110 version SKIROC2 it consists of 64 channels in AMS  $0.35 \mu\text{m}$  SiGe technology. A schematic view

111 of the analog part of the SKIROC2 is shown in Figure 1. Each channel comprises a low noise charge  
112 preamplifier of variable gain followed by two branches: a fast shaper for the trigger decision and a  
113 set of dual gain slow shapers for charge measurement. The gain can be controlled by modifying the  
114 feedback capacitance during the configuration of the detector. With the lowest gain, 6pF, the ASIC  
115 will handle a linear dynamic range from 0.1 to up to 1500 MIPs. Finally, a Wilkinson type analogue  
116 to digital converter fabricates the digitized charge deposition that can be readout. Once one channel  
117 is triggered, the ASIC reads out all 64 channels adding a bit of information to tag them as triggered  
118 or not triggered and the information is stored in a 15 cell deep physical switched capacitor array  
119 (SCA).

120 The SKIROC ASICs can be power-pulsed by taking advantage of the ILC spill structure: the  
121 bias currents of the ASIC can be shut down during the idle time between bunch trains. With this  
122 method, the ASIC is able to reduce its power consumption down to 25  $\mu\text{W}$  per channel, meeting  
123 the ILC requirements. The power pulsing feature is used for all the results discussed in this paper  
124 and for first time in long periods of data taking in beam test.

### 125 **2.3 Active Sensor Units**

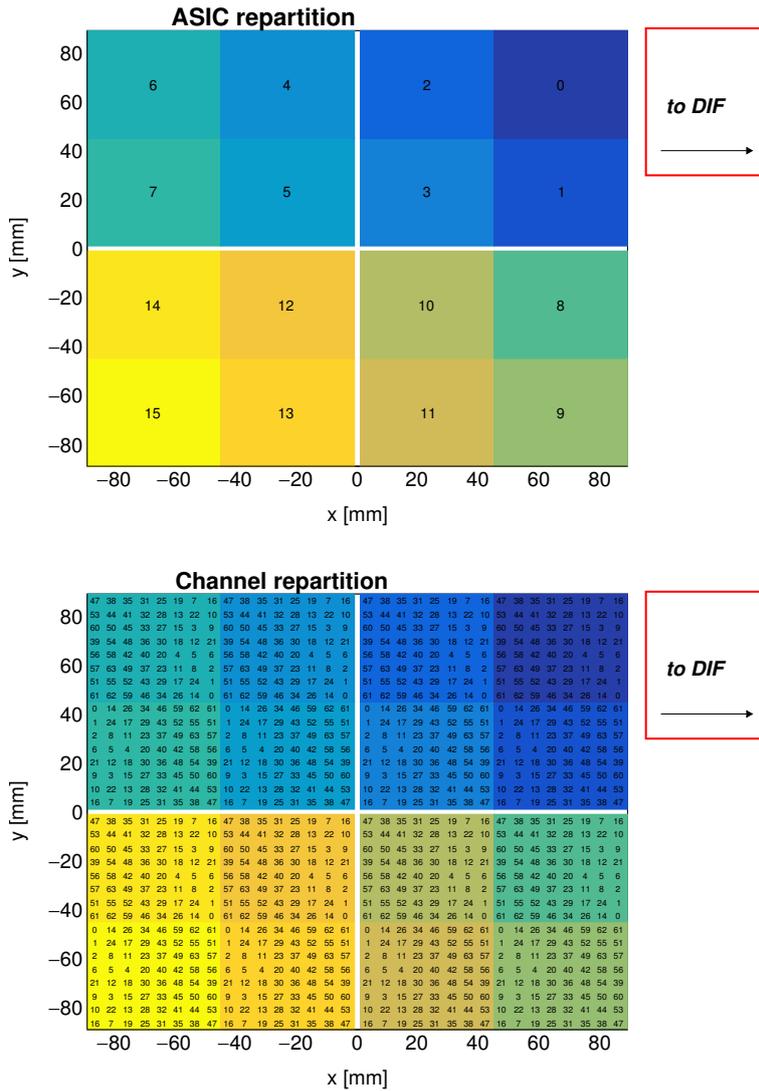
126 The entity of sensors, thin PCB (printed circuit boards) and ASICs is called Active Signal Units or  
127 ASU. An individual ASU has a lateral dimension of 18x18 cm<sup>2</sup>. The ASUs are currently equipped  
128 further with 16 SKIROC2 ASICs for the read out and features 1024 square pads (64 per ASIC) of  
129 5x5 mm. The channels and ASICs are distributed along the ASU as shown in Figure 2. Each ASU  
130 is equipped with 4 silicon wafers as the described in Section 2.1. The high voltage is delivered to  
131 the wafers using a HV-kapton sheet that covers the full extension of the wafers.

132 The current version of the PCB is called the FEV11. It has a thickness of 1.6mm which grows  
133 up to 2.7mm when the ASICs in its current packaging (1.1 mm thick LFBGA package) are bonded  
134 in top of it. With these characteristics, a potential density of 4300 channels/dm<sup>3</sup> is achievable  
135 keeping the space and interaction length requirements of the the baseline design of the ECAL for the  
136 ILD. This number should be compared with the density achieved in beam tests with the physics  
137 prototype: 1500 channels/dm<sup>3</sup>. With the first versions of the technological prototype we reached  
138 similar potential density level as in the current version but equipping only a quarter of the ASUs  
139 surface [24].

### 140 **2.4 Data Acquisition system**

141 The subsequent chain of the data acquisition (DAQ)[21] system consists of three components. They  
142 are enumerated from upstream to downstream from the data flow perspective:

- 143 1. The first component is the so called detector interface (DIF) which is placed at the beginning  
144 of each layer holding up to 15 ASUs.
- 145 2. All DIFs are connected by single HDMI cables to the concentrator cards as the second  
146 component: the Gigabit Concentrator Cards (GDCCs). These cards are used to control up to  
147 7 DIFs. They collect all data from the DIFs and distribute among them the system clock and  
148 fast commands.



**Figure 2.** Repartition of the ASIC (up) and channels (down) in one ASU. In this perspective, the PCB is in the top and the sensors are in glued in the back. The channels are separated (in x and y) by 5.5 mm. The empty cross in the middle of the ASU corresponds to the 1 mm separation between the sensors. The areas covered by the different ASICs and channels are labeled with numbers following design and DAQ criteria: from 0-16 in the case of the ASICs and from 0-63 in the case of the channels.

- 149 3. The most downstream component, is the clock and control card (CCC) which provides a  
 150 clock, the control fan-out of up to 8 GDCCs and accepts and distributes external signals (i.e.  
 151 signals generated external pulse generator to simulate the ILC spill conditions).

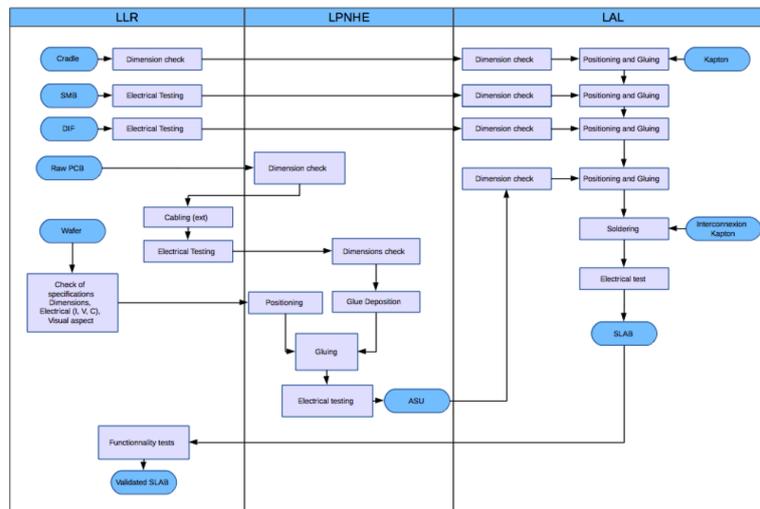
152 The whole system is controlled by the Calicoes and the Pyrame DAQ software version 3 [22, 23].

### 153 2.5 Fully equipped readout modules: the SLABs

154 A fully equipped readout module is shown in Fig. 3. These modules are called SLABs and consist  
 155 of a chain of one or several fully equipped ASUs connected to a data acquisition system (DAQ)



**Figure 3.** Open single SLAB with FEV11 ASU, 16 SKIROC 2 and the interface card visibles.



**Figure 4.** Process flow for the assembly of the SiW-ECAL SLABs.

156 through an adapter board, called SMBv4. The SMBv4 also serves as to hold other services as power  
 157 connectors or the super capacitances used for the power pulsing. These capacitances of 400mF  
 158 with 16 mΩ of equivalent serial resistance are extra dimensioned to provide enough local storage  
 159 of power to assure stable low voltage levels during the power pulsing. The readout modules are  
 160 embedded on a "U" shaped carbon structure to protect the wafers. The full system is then covered  
 161 by two aluminum plates to provide electromagnetic shielding and mechanical stability.

162 For the production of the small sample of SLABs studied in this document, a scalable working  
 163 procedure has been established among several groups [25] profiting from the funding of projects like  
 164 AIDA2020 or the HIGHTEC emblematic project of the P2IO. A schematic view of this assembly  
 165 procedure chain can be seen in Figure 4. For more details we refer to Ref.[25]. This process is to  
 166 be extrapolated to a full assembly procedure for e.g. the ILD detector.

## 167 2.6 The prototype setup

168 A picture showing the SiW-ECAL technological prototype setup can be seen in Figure 5. The  
169 current prototype consists on 7 layers of SLABs housed in a PVC and aluminum structure that can  
170 host up to 10 layers in slots separated by 15mm each. The first six layers were placed in the first six  
171 slots and the last one was in the last slot, with respect to the beam pipe. In the following sections,  
172 we will refer to layers number 1 to 7, where the 1 is the closest to the beam pipe and 7 is the farthest.  
173 This setup is used for commissioning (Section 3) and for the beam test (Section 4). In both cases,  
174 the detector was running in power pulsing mode.

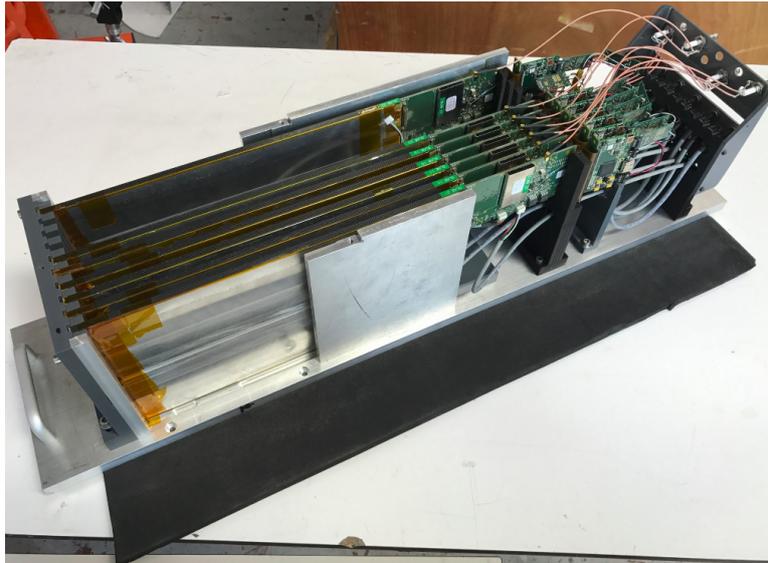


Figure 5. Prototype with 7 layers inside the aluminum stack.

## 175 3 Commissioning

176 Earlier experiences with the SKIROC2 ASIC are reported in Refs. [24, 26]). Internal SKIROC2  
177 parameters reported in these references are adopted in the following unless stated otherwise. For  
178 example, a gain value of 1.2pF for the preamplifier is used. With this gain, the SKIROC2 features a  
179 linearity better than 90% for 0.5-200 MIPs, which is sufficient for electromagnetic showers created  
180 by few GeV electrons or positrons.

181 The main goal of the the commissioning procedure is the optimization of the trigger thresholds  
182 to levels in which we are able to record physics signals bellow the MIP level without saturating our  
183 DAQ with noise signals. This requires a careful and systematic procedure to:

- 184 1. identify the readout channels that are noisy in high trigger threshold above MIP signal  
185 conditions;
- 186 2. and select the optimal trigger threshold levels.

187 During the commissioning, we observed the repetition of coherent noise events affecting to  
188 several SLABs at the end of acquisitions with long gating time. The situation could be remedied

189 by improving the isolation of the individual SLABs and by reducing the data taking to short gating  
 190 times. In any case, all runs dedicated to the commissioning are usually characterized by their short  
 191 gating windows for the acquisition (1-2ms) at low repetition frequencies (1-5 Hz) to minimize the  
 192 chances of having real events due to cosmic rays during the data taking.

### 193 **3.1 Tagging and control of the noisy channels.**

194 The list of the noisy channels was obtained by means of dedicated data taking runs. In these runs  
 195 we scan relatively high trigger thresholds (between 1-3 MIPs) and progressively mask channels that  
 196 exhibit counts. In each step, the decision of tagging a channel as noisy was taking following the  
 197 next rules:

- 198 • if the channel was triggered at rates larger than 0.5-1% of the total number of triggers per  
 199 ASIC it was added to the list;
- 200 • if a channel was tagged as noisy in, at least, three of the SLABs, it was tagged as noisy for all  
 201 and added to the list of channels being suspect of suffer from routing issues.

202 Following this procedure, we found to different types of noisy channels. One set consists of  
 203 channels randomly distributed along the surface of every ASU and the other consists of channels  
 204 located in specific areas and systematically noisy in all the ASUs. Preliminary inspections of the  
 205 PCB layout hint that the channels in the latter set may be noisy due to improvable routing of the  
 206 PCB. Deeper studies on the PCB routing must be conducted to clarify this. All the noisy channels  
 207 have been identified and masked and the power of their preamplifiers has been disabled. All the  
 208 results shown in the following sections are obtained in these conditions.

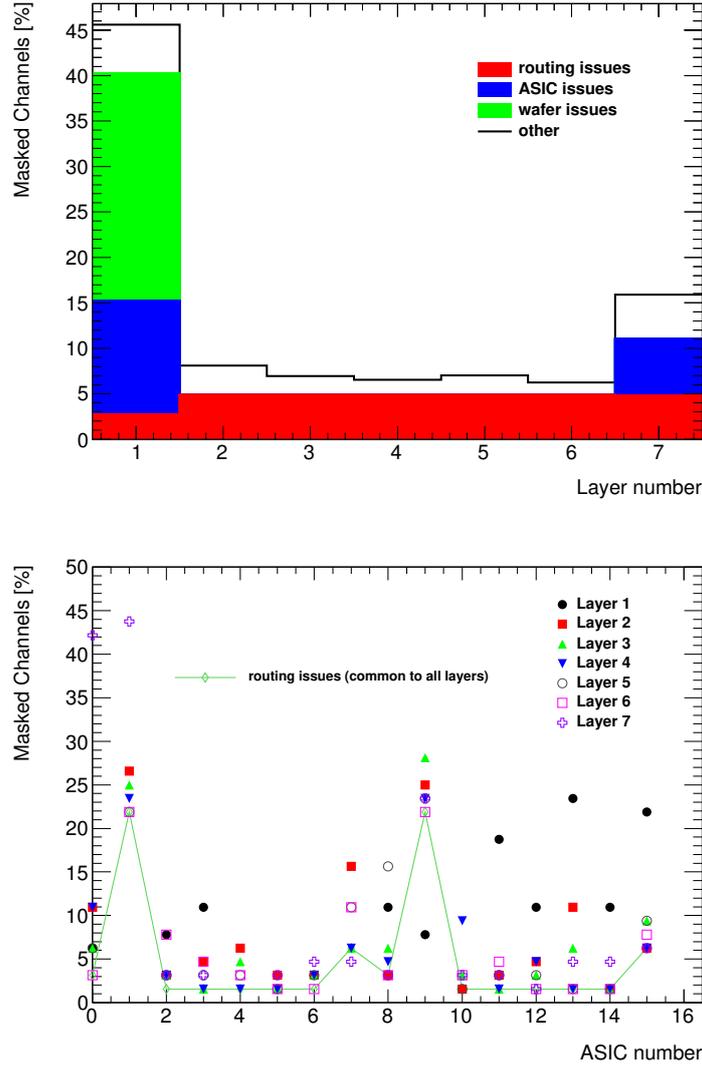
209 In addition to the different noisy channel types described above, we also have masked full  
 210 sectors of the SLABs if an ASIC was tagged as faulty (at least 70% of channels listed as noisy) or if  
 211 a Si-wafer was damaged (high leakage currents). The results of this study is summarized in Figure  
 212 6.

### 213 **3.2 Optimal trigger threshold determination**

214 After the noisy channels have been masked, dedicated trigger threshold scan runs are taken, and  
 215 the results are shown in the threshold scan curves where the x-axis represents the threshold value  
 216 and the y-axis the number of recorded signals normalized to 1. The threshold values are given  
 217 in internal DAC units which are translated to meaningful physical quantities in Section 3.3. In  
 218 the absence of external signals (cosmic rays, injected signals, etc) the falling edge position in the  
 219 threshold scan curves is due to the electronic noise at the output of the fast shaper (the trigger  
 220 decision branch on the SKIROC) and it depends on the slow clock frequency. These threshold scan  
 221 curves are approximated by a complementary error function:

$$\frac{2p_0}{\sqrt{\pi}} \int_{\frac{DAC-p_1}{p_2}}^{\infty} e^{-t^2} dt, \quad (3.1)$$

222 where  $p_0$  is 1/2 of the normalization,  $p_1$  is the value in which the noise levels are the 50% of its  
 223 maximum and  $p_2$  give us the width of the threshold scan curve. In Figure 7 two threshold scans  
 224 curves are shown together with the fit by the theoretical function.



**Figure 6.** Fraction of channels that are tagged as noisy in all slabs. Top: different type of noisy channels per slab. Bottom: break down of the total number of noisy channels per ASIC. The ASICs 4-7 (wafer issue) and 10 from layer 1 and the ASIC 4 from layer 7 are not included in the second plot since they are fully masked.

225 For every ASICs, after performing the fit of the theoretical curves to the threshold scans, the  
 226 average values of the  $p_1$  and  $p_2$  are calculated. These are represented by  $\langle p_{1,2}^{ASIC} \rangle$  in the following.  
 227 The optimal threshold value of every ASIC, in DAC units, was chosen using the following formula

$$DAC_{optimal}^{ASIC} = maximum(\langle p_1^{ASIC} \rangle + 5 \times \langle p_2^{ASIC} \rangle, 230). \quad (3.2)$$

228 This formula was applied if at least the the 30% of the 64 channels in the ASIC could be fitted. If  
 229 not, a global threshold value of 250 was set.

230 The optimal trigger threshold values for all ASICs are shown in Figure 10, in internal DAC  
 231 units and in MIPs. In the next section we explain how the conversion is done.

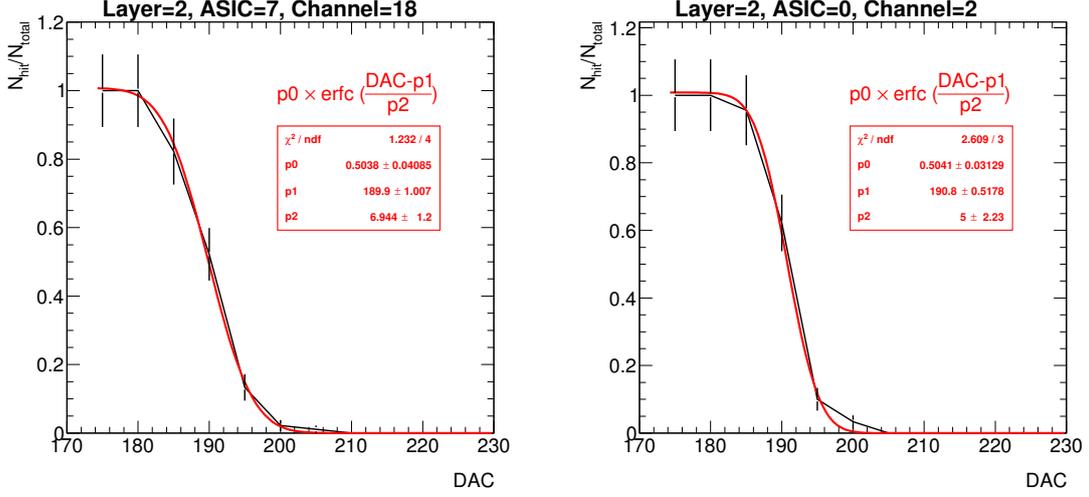


Figure 7. Two threshold scan curves.

### 232 3.3 S/N ratio for the trigger decision

233 Performing threshold scan curves using real signals allow to calculate the signal over noise (S/N)  
 234 ratio for the trigger decision. For that we compare the curves for 1 MIP and 2 MIP injected signals.  
 235 The  $S/N(\text{trigger})$  is, in the following, defined as the ratio between the distance of both curves at its  
 236 50% and the width of the curves. In Figure 8 we see the 1 MIP and 2 MIP curves obtained for  
 237 several channel in a SKIROC testboard in which a single SKIROC2 in BGA package is placed and  
 238 the 1 MIP and 2 MIPs signals are directly injected in the preamplifier (via a 3 pF capacitor located  
 239 in the injection line as shown in Figure 1).

240 We have obtained similar results using real signals, in this case cosmic rays signals. This is  
 241 shown in Figure 9 where we show the result of the fit to the threshold scan curves cosmic rays  
 242 integrated for all channels in one ASIC. For completeness, the fit of threshold scan curves for all  
 243 channels in the same ASIC are also shown.

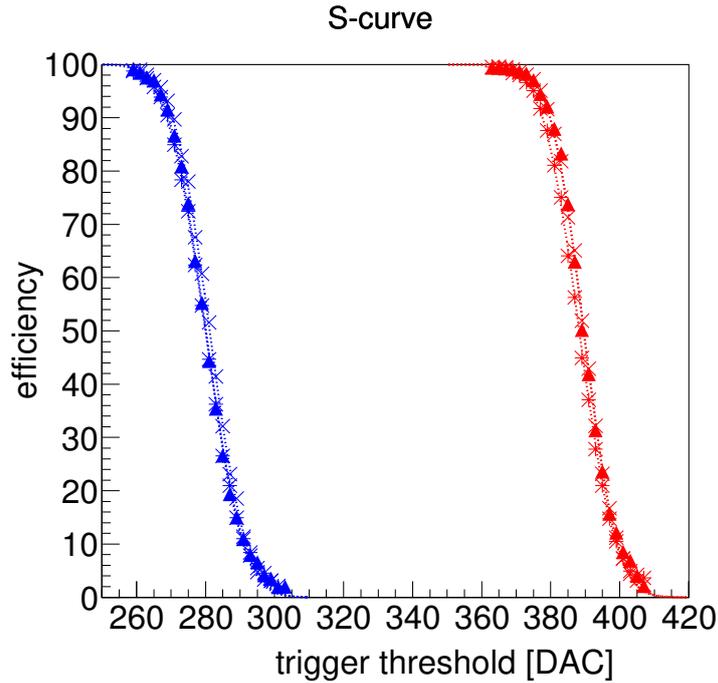
244 From these two results we extract the value of

$$S/N(\text{trigger}) = 12.9 \pm 3.4 \quad (3.3)$$

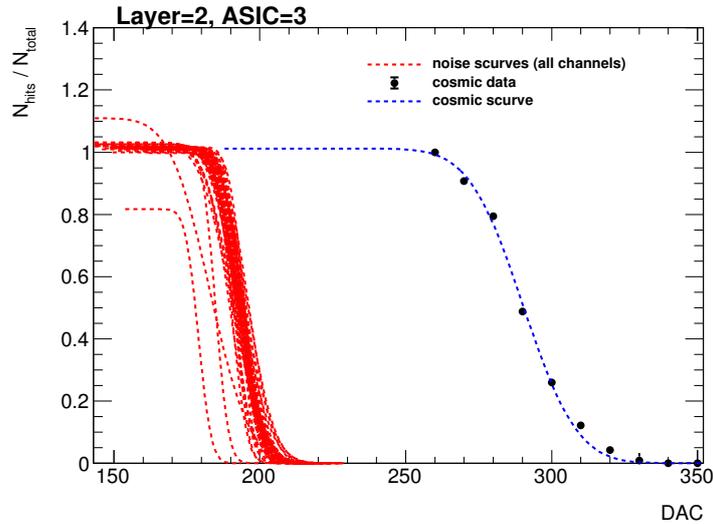
245 for the trigger branch. The central value is calculated from Figure 1 by the comparison of the 1 and  
 246 2 MIP curves and using the width of the 1 MIP curve in the denominator. The estimated uncertainty  
 247 has two components: the difference of width between the 1 and 2 MIP curves of injected signals  
 248 and the differences (width and middle point) between the 1 MIP curves for injected and cosmic  
 249 ray signals. With this value of the S/N we are able to trigger the detector with small signals of the  
 250 size of  $\sim 0.5$  MIP. This is seen in in Figure 10, where the chosen thresholds of every ASIC being  
 251 tested in beam are shown. However dedicated studies in beam test are needed in order to reduce the  
 252 uncertainty of this measurement.

### 253 3.4 Prospects

254 The commissioning procedure described above relies on very conservative decisions due to the  
 255 presence of unknown noise sources during largest of the commissioning phase. These sources

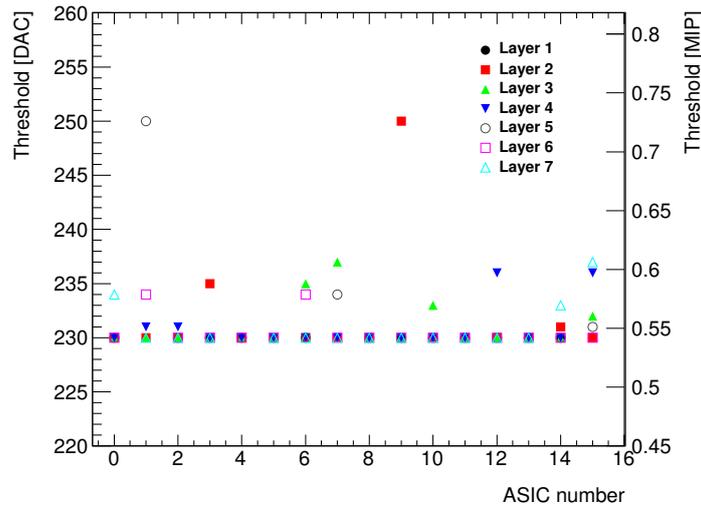


**Figure 8.** Threshold scan curves with charge injection (1 MIP in blue and 2 MIPs in red) for two different channels in a SKIROC2 testboard.



**Figure 9.** Threshold scan curves for noise (channel by channel, only the result of the fit) and cosmic rays (all channels together) for one ASIC in layer 2.

256 are now well know and therefore a new noise commissioning procedure has been studied. It will  
 257 consist on an iterative algorithm that first will identify and mask the channels in which the number  
 258 of triggers per channel will be compared with the number of expected triggers assuming only  
 259 cosmic rays as signal. This will allow us to have a definition of the noise levels for each channel



**Figure 10.** Summary of the trigger threshold settings in internal DAC units and in MIP units.

260 independently instead of relatively to the total number of triggers recorded by the ASIC. Finally,  
 261 once the noisy channels are identified, the threshold are further optimized with a last run for the  
 262 identification of the residual noisy channels.

263 Using this new procedure we manage to reduce the number of masked channels by a factor of  
 264 two without any loss of performance, at least in the laboratory and using 3 of the 7 SLABs. This new  
 265 procedure will also be applied in the next beam test. Also, in order to optimize the commissioning  
 266 of the detector, we propose a new set of measurements in the next beam test such as a threshold  
 267 scan for the determination of the S/N in the trigger line. The later can be done by the comparison of  
 268 threshold curves taken with incident MIP-acting particles and MIP-acting particles traversing the  
 269 detector tilted by 45 degrees with respect to the beam direction.

#### 270 **4 Performance in a beam test with positrons at DESY**

271 The beam line at DESY provides continuous positron beams in the energy range of 1 to 6 GeV with  
 272 rates from a few hundreds of Hz to a few kHz with a maximum of  $\sim 3$  kHz for 2-3 GeV. In addition,  
 273 DESY gives access to a bore 1 T solenoid, the PCMag.

274 The physics program of the beam test can be summarized in the following points:

- 275 1. Calibration without tungsten absorber using 3 GeV positrons acting MIPs directed to 81  
 276 position equally distributed over the modules.
- 277 2. Test in magnetic field up to 1 T using the PCMag. For this test a special PVC structure was  
 278 designed and produced to support one single SLAB. The purpose of such test was twofold:  
 279 first to prove that the DAQ, all electronic devices and the mechanical consistency of the SLAB  
 280 itself are able to handle strong magnetic fields; second to check the quality of the data and  
 281 the performance of the detector during the data taking when running in a magnetic field.

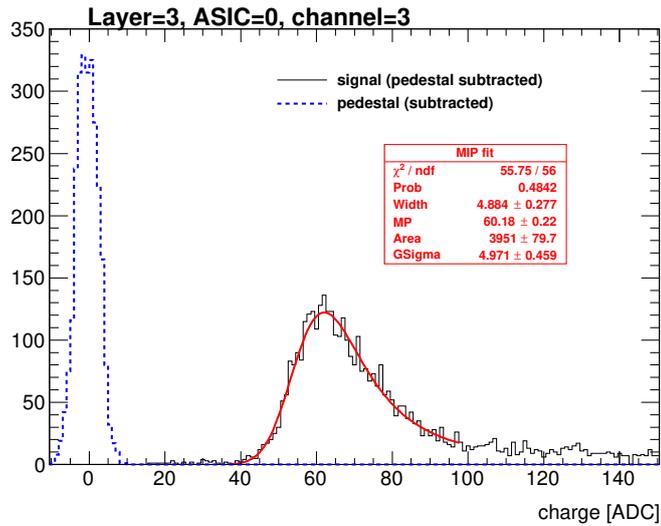
282 3. Response to electrons of different energies with fully equipped detector, i.e. sensitive parts  
 283 and W absorber, with three different repartitions of the absorber material:

- 284 • W-configuration 1: 0.6, 1.2, 1.8, 2.4, 3.6, 4.8 and 6.6  $X_0$
- 285 • W-configuration 2: 1.2, 1.8, 2.4, 3.6, 4.8, 6.6 and 8.4  $X_0$
- 286 • W-configuration 3: 1.8, 2.4, 3.6, 4.8, 6.6, 8.4 and 10.2  $X_0$

287 First reports on this beam test can be find in Refs. [27, 28]. These results have extended  
 288 and are discussed in the following sections. In Section 4.1 we discuss in detail the results of the  
 289 pedestal, noise and MIP calibration. We show also results on the pedestal and noise stability when  
 290 running inside a magnetic field in Section 4.2 and in electromagnetic shower events in Section 4.3.  
 291 The study of the calibration of the prototype in electromagnetic shower events is due to a future  
 292 publication.

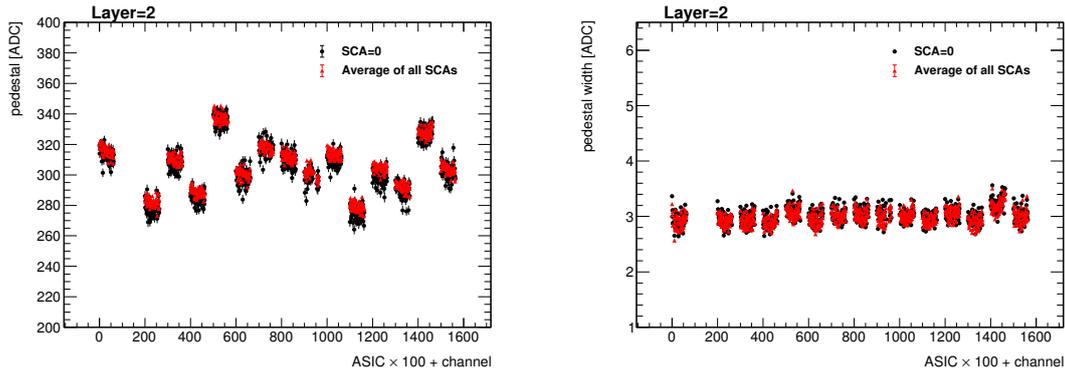
#### 293 4.1 Noise study and MIP calibration

294 In Figure 11 we show the signal and pedestal distribution of a single channel after subtracting  
 295 the pedestal mean position. The results of the MIP calibration fit are shown in red. The signal  
 296 distribution is integrated over all SCAs. For cosmetic reasons the pedestal distribution is shown  
 297 only for the first SCA.

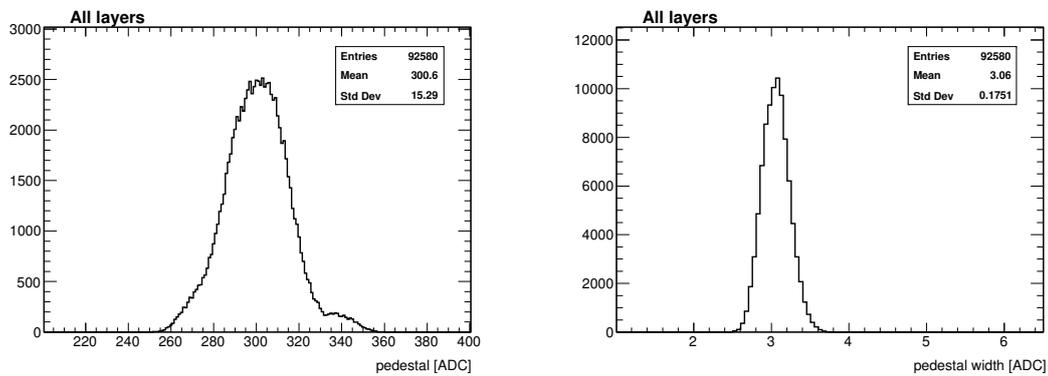


**Figure 11.** Pedestal (blue dashed line) and signal (black continuous line) distribution for one channel in the third layer.

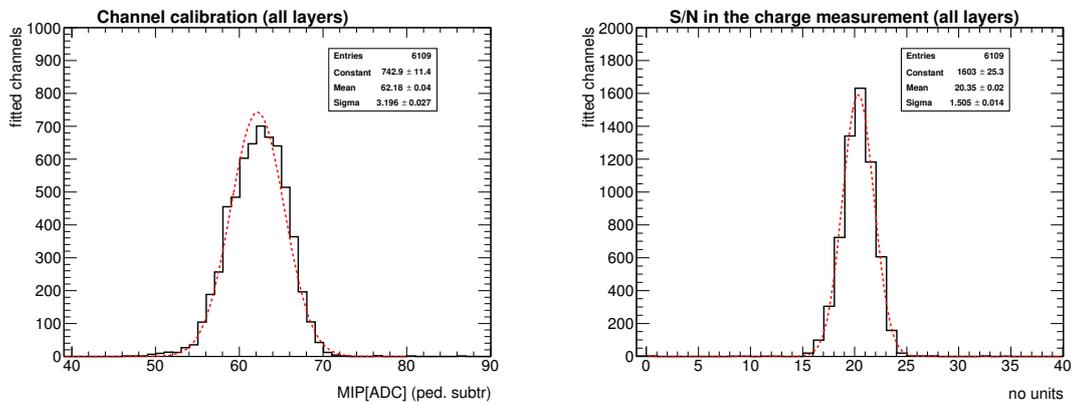
298 The pedestal is calculated as the mean position of the distribution of the ADC values for all  
 299 channels without trigger. The noise is associated to the width of the distribution. The pedestal  
 300 correction is done layer-, chip-, channel- and SCA-wise due to the large spread of values between  
 301 pedestals, as observed in Figure 12 (left plot) and Figure 13 (also left plot). For the noise, the  
 302 dispersion is much smaller ( $\sim 5\%$ ). This is shown in the right plots of Figures 12 and 13. From  
 303 now on, the pedestal correction is applied to all the results presented. The resulting spectra are



**Figure 12.** Pedestal mean position (left plot) and width (right plot) for all channels in one layer.



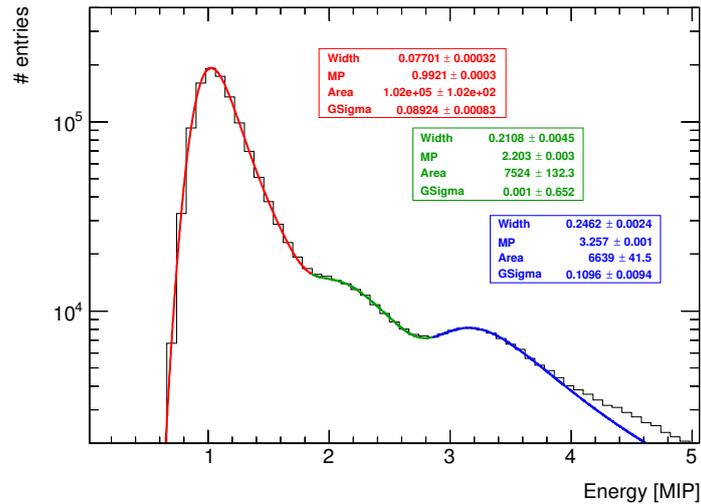
**Figure 13.** Pedestal mean position (left) and width (right) for all channels and all SCAs in the setup.



**Figure 14.** Result of the MIP position calculation and signal over noise calculation for all calibrated channels.

304 fit by a Landau function convoluted with a Gaussian. The most-probable-value of the convoluted  
 305 function is taken as the MIP value, allowing thus for a direct conversion from ADC units to energy  
 306 in MIP units. The fit succeeded in 98% of the cases and the spread of the resulting MPV is 5%.  
 307 The remaining channels will be discarded. Results are summarized in figure 14, leftmost plot.

308 The Figure 15 shows the response of all channels integrated over the calibration run. This plot



**Figure 15.** Energy distribution for all calibrated channels when selecting incident tracks of 3 GeV positron acting as MIPs.

309 is obtained after further refinement of the sample by selecting incident tracks. The maximum peaks  
 310 at 1 MIP as expected after a good calibration. In addition to this, a second and a third peaks are  
 311 visible as shoulders. These shoulders are associated to events involving multiple particles crossing  
 312 the detector.

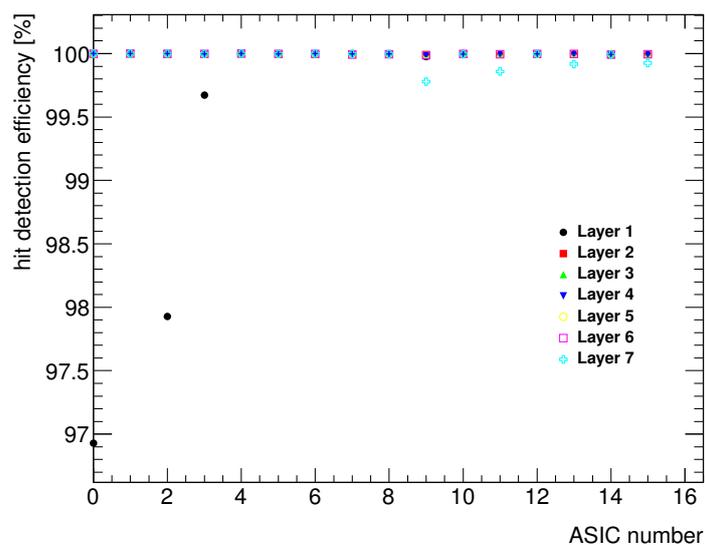
313 To evaluate the single hit detection efficiency we define a high purity sample of events by  
 314 selecting tracks with at least 4 layers with a hit in exactly the same channel. Afterwards we check  
 315 which layers have or not a hit in the same or in the closest neighboring channels with energy larger  
 316 or equal than 0.3 MIP. We repeat this procedure for all channels. The results are shown in Figure  
 317 16. Except few exceptions, the efficiency is compatible with 100%. The low efficiencies in the first  
 318 layer are related to the presence of noisy channels not spotted during the commissioning. These  
 319 channels may saturate de acquisition in their ASICs. In the last layer we also observe a few small  
 320 deviations which are associated to the outliers channels, hinting for a small misalignment of the last  
 321 layer.

#### 322 4.1.1 S/N for charge measurement

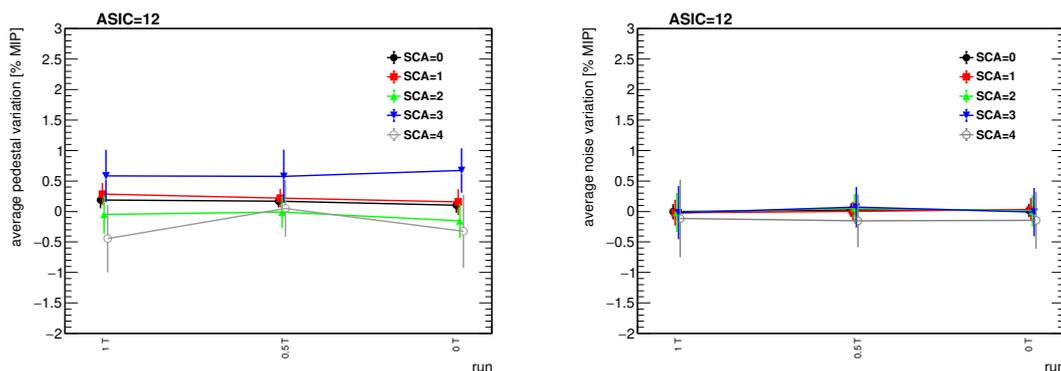
323 The S/N(charge) for the charge measurement of cells readout by an ASIC that has recorded a trigger  
 324 is defined as the ratio between the most-probable-value of the Landau-gauss function fit to the  
 325 data from MIP scan runs and the noise (the pedestal width). This quantity has been calculated for  
 326 all channels and all layers. Results are summarized in Figure 14, rightmost plot. This definition  
 327 corresponds to the S/N of the SiW-ECAL technological prototype quoted in past references, *i.e.*  
 328 Ref. [24]. This value of the S/N(charge) shows that, if a trigger is present, we will be able to  
 329 measure very low energies, *i.e.* 0.2-0.25 MIP, in the other cells.

#### 330 4.2 Pedestal and noise stability in a magnetic field

331 The data taking inside the magnetic field has been divided in three runs:



**Figure 16.** MIP detection efficiency for all layers and ASICs in high purity samples of tracks of MIP-like acting particles.



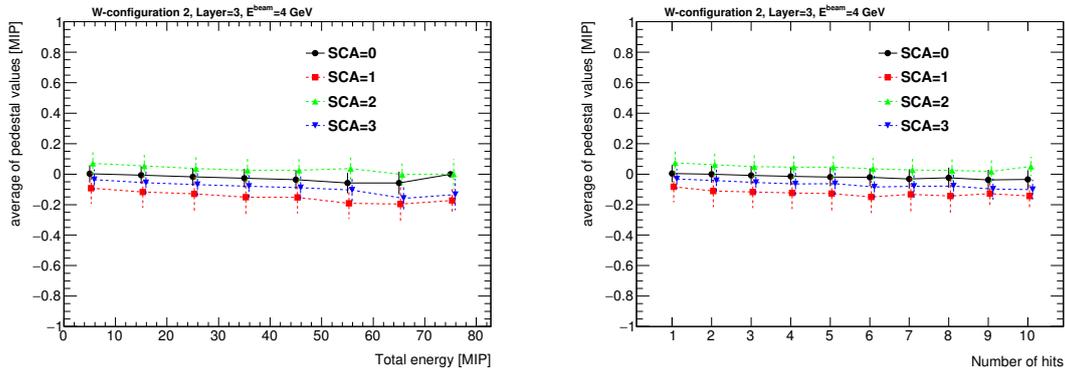
**Figure 17.** Average deviation of the pedestal mean position (left) and width (right) for all channels in the ASIC 12.

- 332 1. a with a magnetic field of 1 T;
- 333 2. a run with 0.5 T;
- 334 3. and a final run with the magnet off.

335 The beam, 3 GeV positrons, was directed in the area of the PCB readout by the ASIC number  
 336 12. The pedestal positions and noise levels of the channels of the ASIC 12 when the SLAB is inside  
 337 of the PCMag are compared with the results from the calibration run described in the previous  
 338 section. This is shown in Figure 17. We see that the agreement is perfectly good within the  
 339 statistical uncertainties. Due to the lower rates in this beam area, the analysis is only done up to few  
 340 SCAs.

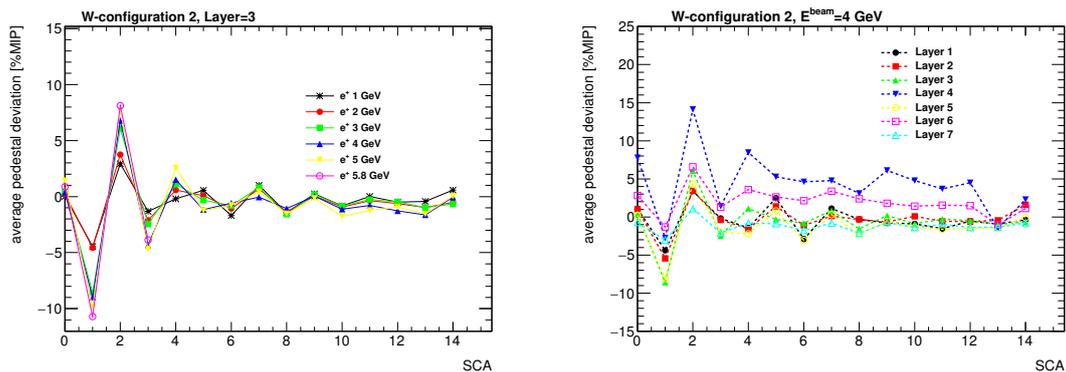
### 341 4.3 Pedestal stability in electromagnetic shower events

342 In this section we discuss the pedestal stability in events with large amount of charge collected by the  
 343 ASICs, as are the electromagnetic shower events. All the results shown in this section correspond  
 344 to data taken during the tungsten program, using the W-configuration number 2 when shooting the  
 345 beam in the area registered by the ASIC 12 (and partially in the 13). For simplicity, only information  
 346 recorded by ASIC 12 will be shown. In order to select a high purity of electromagnetic shower like  
 347 the events, we used a simple criteria: select only events with at least 6 of the layers with at least a  
 348 hit with  $E > 0.5$  MIP.



**Figure 18.** Left: mean position of the projection of the pedestal distribution of all channels calculated when different energies are collected in the ASIC (in bins of 10 MIPs). Right: same but as a function of the number of hits. In both cases, the results are shown for few SCA. The points for the curves with SCA different than zero are slightly shifted in the x-axis to optimize the visualization.

349 Two main observations have been extracted from the recalculation of the pedestals and its  
 350 comparison with the values obtained previously during the calibration runs. The first observation  
 351 consists in a relatively small drift of the pedestal values towards lower values when the collected  
 352 energy is high *i.e.* when the number of triggered channels is large. This is shown in Figure 18 for  
 353 several SCAs. A small dependence, in all SCAs, of the pedestal position on the amount of charge  
 354 collected by the ASIC is observed. This feature is known and it is due to the architecture of the  
 355 SKIROC2 ASICs where high inrush of currents can slightly shift the baseline of the analogue power  
 356 supply. The second observation extracted from this analysis can be also seen in Figure 18 but more  
 357 clearly in Figure 19: in addition to the small drift of the pedestal value an SCA-alternate global  
 358 shift is observed. We see that the effect is enhanced when large amounts of charge are deposited  
 359 in the ASIC (*i.e.* at larger beam energies or for the layers in the maximum of the shower profile).  
 360 We also observed that this alternation is only SCA dependent and does not depends on the time in  
 361 which the deposit of energy occurs within the acquisition. This is not yet fully understood although  
 362 the fact that the effect is observed in alternate SCAs hints that something is affecting to the digital  
 363 part of the ASIC (where the SCAs enter in play). Dedicated tests in the laboratory and in the beam  
 364 are needed in order to clarify this issue.



**Figure 19.** Average value over all channels in ASIC 12 of the pedestals position for each SCA in electromagnetic shower events.

## 5 Summary

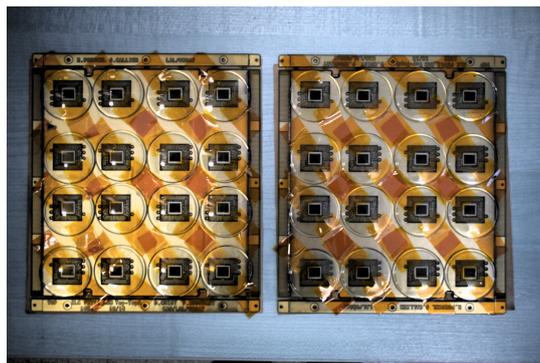
The R&D program of the highly granular SiW-ECAL detector is in an exciting phase. After the proof of principle of the imaging calorimetry concept using the physics prototype, the technological prototype is being constructed and tested. In this document we describe the commissioning and beam test performance of a prototype built in with the first fully assembled detector elements, in contrast with previous beam tests. In addition, with the setup used in this beam test we reached levels of granularity similar to the targets of the ILD detector for the ILC. This is also the first time that a SiW-ECAL prototype continuously takes data in a beam test running in power pulsing mode, one of the crucial features for the detectors for the ILC. Finally, we tested the performance of the detector modules working for long periods inside magnetic fields.

A very comprehensive and detailed commissioning procedure has been established and optimized allowing us to identify and isolate the different noise sources that could spoil the data taking. The beam test has provided a lot of useful data to study the performance of the detector and to perform a channel by channel calibration, showing a good homogeneity with a spread of the 5% for all channels. Two S/N quantities are calculated: one for trigger decision,  $12.9 \pm 3.4$ , and a second one for charge measurement when a trigger has been already set,  $20.4 \pm 1.5$ .

## 6 Outlook

In parallel to the work described here, several R&D efforts are being carried. One of these efforts is directed to the design and test of new ASICs. In fact, a new generation of the SKIROC, the 2a, has been delivered, tested in the dedicated testboards and it has been integrated in new ASUs. In addition, a new generation of the ASIC, SKIROC3, is foreseen for the final detector construction. In contrast with SKIROC2/2a, the new ASIC will be fully optimized for ILC operation, *i.e.* full zero suppression, reduced power consumption etc.

Many efforts are also concentrated in the construction and test of long SLABs made of several ASUs enchainned since we know that the ILD ECAL will host long layers of up to  $\sim 2.5$ m. This device constitutes a technological challenge in both aspects, the mechanical (very thin and long structure with fragile sensors in the bottom make complicated the assembly procedure and the



**Figure 20.** Two FEV11\_COB boards with 16 SKIROC2a wire bonded. The ASICs are protected with watch glasses.

392 handling...) and the electrical (we need to ensure and control the transmission of signals and high  
393 currents along the full device). For example, interconnections between ASUs and between ASU  
394 and interface card are one of the most involved parts of the assembly and require close collaboration  
395 between mechanical and electronic engineers. A first long SLAB prototype of  $\sim 8$  ASUs has been  
396 already tested in beam test also in DESY in 2018.

397 In parallel, a different proposal for a thinner ASU design is being investigated. This is motivated  
398 by the high density of channels demanded by the Particle Flow algorithms. In this alternative PCB  
399 design the ASICs are directly placed on board of the PCB in dedicated cavities. The ASICs will be  
400 in semiconductor packaging and wire bonded to the PCB. This is the so-called COB (chip-on-board)  
401 version of the ASU. A small sample of FEV11\_COBs (same connexion pattern with the interface  
402 card than FEV11) with a total thickness of 1.2 mm (to be compared with the 2.7 of the LFBGA  
403 solution in the FEV11) has been produced and tested in the laboratory showing its readiness for  
404 tests with particle beams. A sample can be seen in Figure 20. These new boards maximize the  
405 density of channels ( $6000 \text{ channels/dm}^3$ ) for the ECAL of the ILD and will allow to satisfy the  
406 baseline requirements of the ECAL for the ILD.

407 Finally, intensive R&D on the compactification of the DAQ to meet the tight space requirements  
408 for the ILD is being done by the SiW-ECAL collaboration.

409 It is foreseen that all these developments, with the exception of the SKIROC3, will be tested  
410 with particle beams during 2018-2019.

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419 The measurements leading to these results have been performed at the Test Beam Facility at DESY  
420 Hamburg (Germany), a member of the Helmholtz Association (HGF).

## 421 **A Appendix: Filtering of fake triggers**

422 Several types of fake signals have been observed in the technological prototype since its construction  
423 and test. A detailed description of them can be found in previous articles, as for example, in Ref.  
424 [24]. All these fake signals are easily identified and tagged during the data acquisition and removed  
425 afterwards from the analysis not introducing any significance loss of performance as can be seen,  
426 for example, in the hit detection efficiency plots (see Section 4.1). In the following, we briefly  
427 describe the status of the monitoring, debugging and filtering of such kind of events.

### 428 **Empty triggers**

429 Empty trigger events are a well known feature of SKIROC2. The SKIROC2 uses an OR64 signal  
430 to mark the the change to a new SCA when a signal over threshold is detected. The empty triggers  
431 appear when during the acquisition the rising edge of the slow clock falls during the OR64 signal  
432 and therefore the change to a new SCA is validated twice. This effect creates around 17% of empty  
433 events which are easily filter and removed from the analysis. The ratio of empty triggers in the new  
434 SKIROC2a has been reduced to the  $\sim 2 - 3\%$  by reducing the length of the OR64 signal.

### 435 **Plane events and retriggers**

436 Another well know issue is the appearance of bunches of consecutive fake triggers, called retriggers,  
437 that saturates the DAQ. Although the ultimate reason of the appearance of these events remains not  
438 clear, it is suspected that they are related to distortions of the power supply baselines. We know  
439 that the SKIROC2 and 2a preamplifiers are referenced to the analog power supply level, therefore,  
440 any voltage dip can ve seen as signal by the preamplifiers. Moreover the presence of a high inrush  
441 of current due to many channels triggered at the same time can create these voltage dips and also  
442 produce the so called plane events (most of the channels trigered at once). In previous studies  
443 the ratio of retriggers and plane events was reduced by improving the power supply stabilization  
444 capacitances.

445 Studying the MIP calibration data of this beam test we have noticed that the concentration  
446 of the retriggers and plane events in ASICs far from the beam spot is higher than in the ASICs  
447 that are reading out the information of real hits. We have also observed that the concentration of  
448 these events is higher in the nearby of channels that were masked as suspicious of suffering from  
449 routing issues. The ratio these events have been estimated to be of  $1 - 3\%$  in the ASICs where  
450 high frequency interactions are produced (*i.e.* using 3 GeV positrons ate 2-3 kHz) and at higher  
451 rates even larger than 40% in other ASICs far from the beam spot. Moreover, it has been noticed a  
452 correlation between the time that an ASIC was full and the time of the appearance of some retriggers  
453 in other areas of the PCB. This correlation corresponds to  $\sim 1.6 \mu\text{s}$  which hints of a distortion on  
454 the analogue power supply when the signal that informs the DIF that one ASIC memory is full is  
455 transmitted through the PCB.

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